



CS484 - 63/37 Sn/Pb SOLDER BALLS  
CSG484 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	$\approx$	$\approx$	1.80	3
A <sub>1</sub>	0.30	0.38	0.45	
D/E	19.00 BSC			
D <sub>1</sub> /E <sub>1</sub>	16.80 BSC			
e	0.80 BSC			
φb	0.40	0.50	0.55	
aaa	$\approx$	$\approx$	0.12	
ccc	$\approx$	$\approx$	0.10	
ddd	$\approx$	$\approx$	0.15	
eee	$\approx$	$\approx$	0.08	
M	22			2

### NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. NOMINAL "A" DIMENSION IS TYPICALLY 1.67 mm
4. CONFORMS TO JEDEC MO-205.

## 484-BALL LAMINATE CHIP SCALE BGA, 0.80mm PITCH (CS484/CSG484)

## Revision History

The following table shows the revision history for this document.

Date	Version	Revision
4/2/07	1.0	Initial Xilinx release.